

# SerDes and its Role in Future Designs



**TERASPEED<sup>®</sup>**  
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# Serdes / Differential Pair

## The Future of High Speed Designs

- PCB material
- Stackup
- Crosstalk
- FWE (Fiber Weave Effect)
- Stubs & backdrilling
- Surface roughness
- IL/RL/FEXT/NEXT (Insertion/Return Loss/Crosstalk)
- BOR (Break Out Region) or signal launch
- DC blocking cap planes
- Bypass/Decoupling mounting inductance

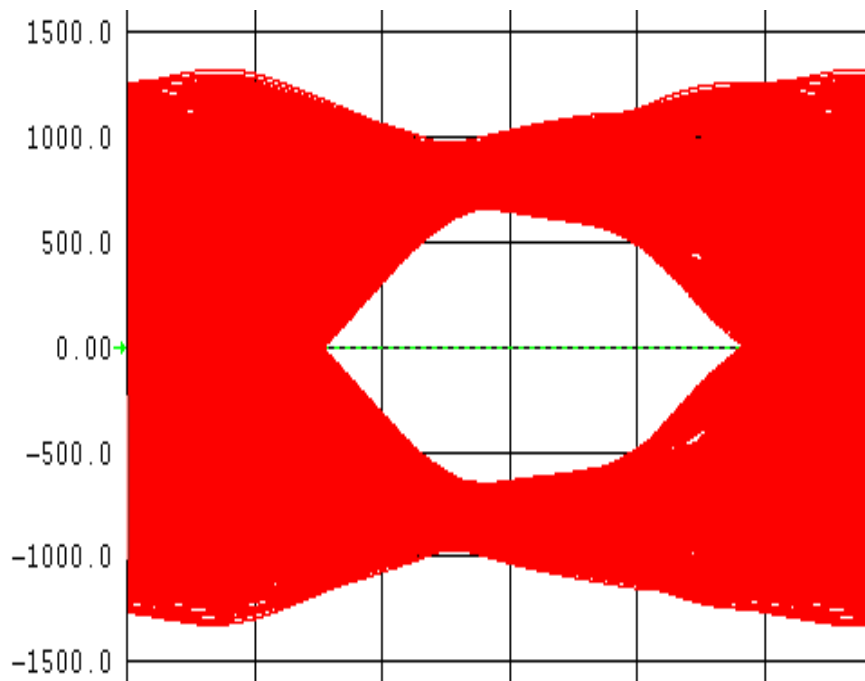


# Differential Pair Skew

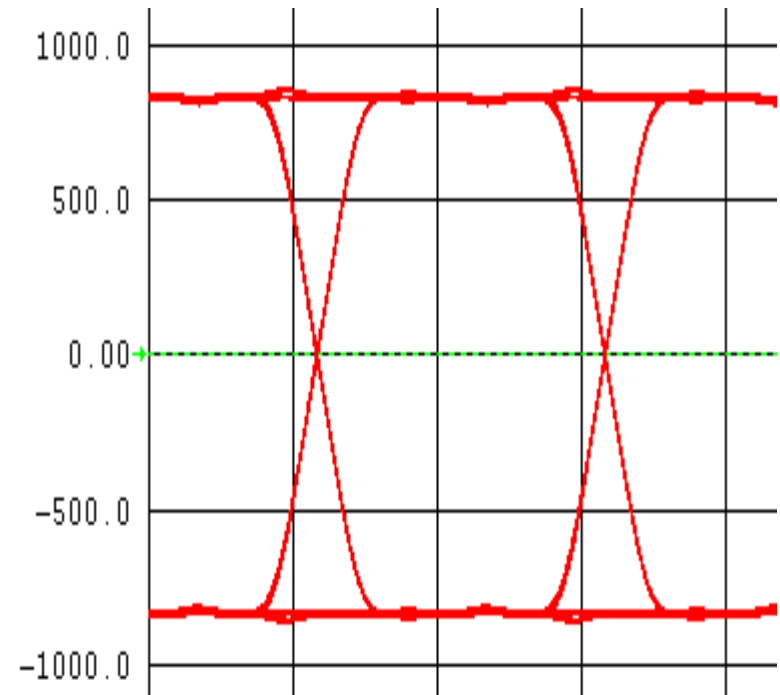
Equal Skew – Slower Frequency &  $t_{\text{rise}}$



200 mil / 5 mm - Skew at driver



10 Gb/s

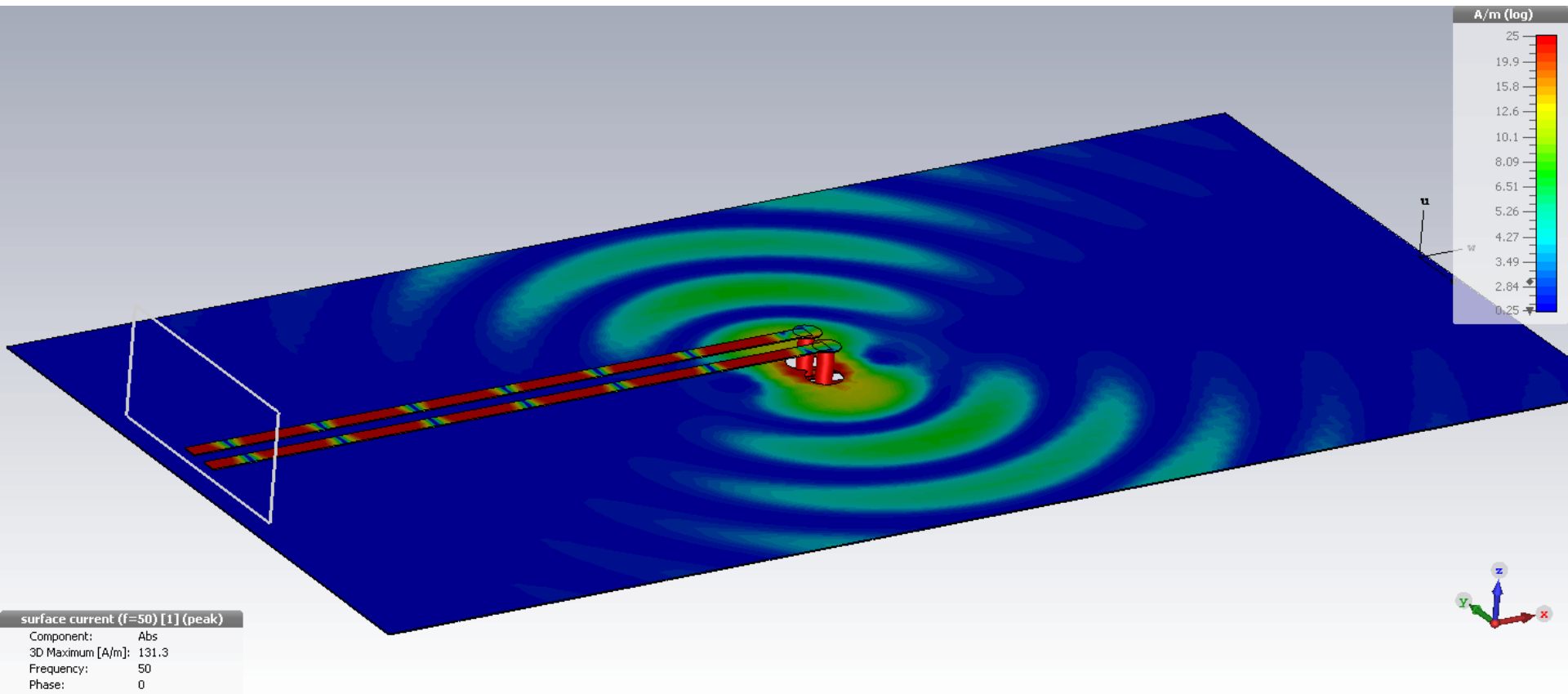
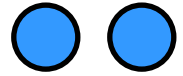


1 Gb/s



# Reference Connectivity

## No Return Currents Path

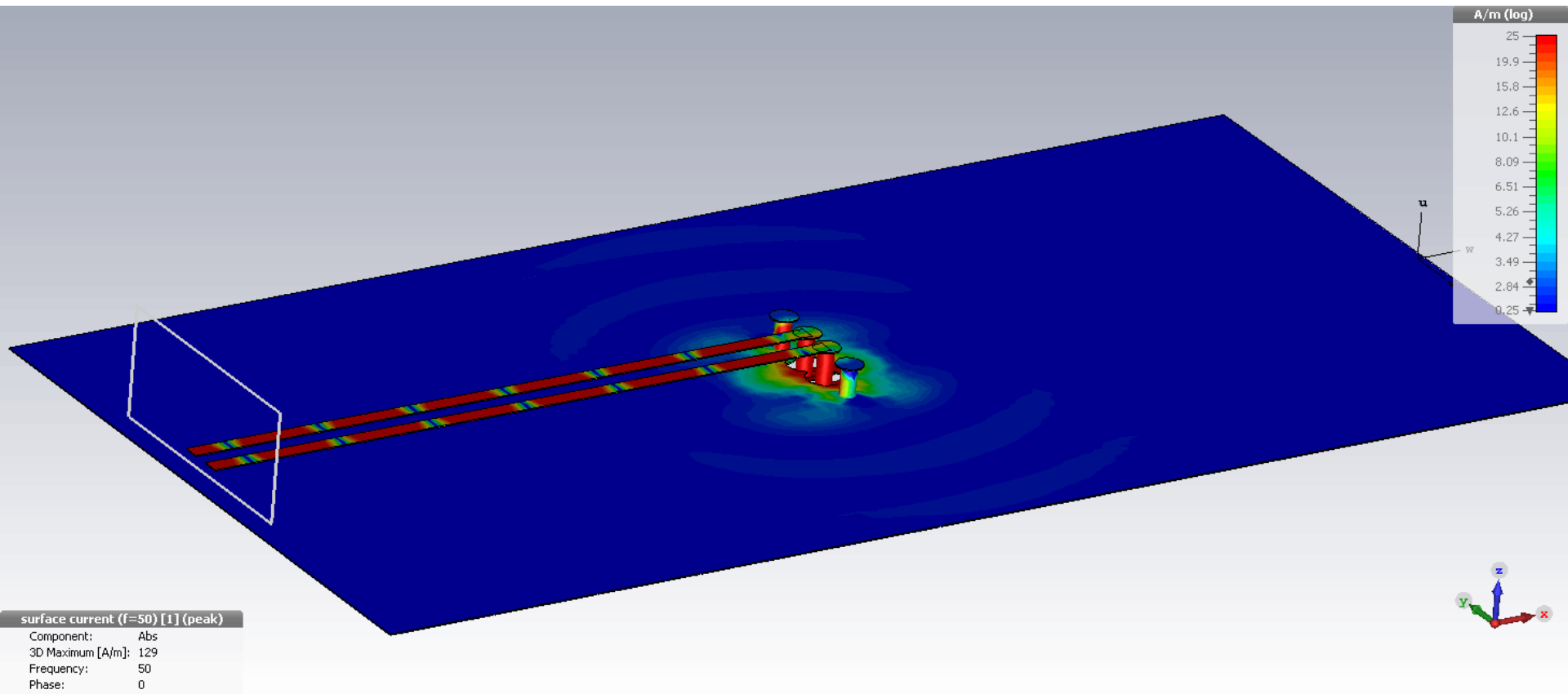
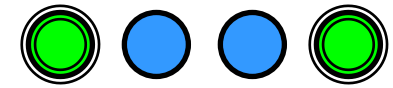


Differential pair with **no** via stitching  
No return current path close



# Reference Connectivity

## Stitching Vias for Return Currents

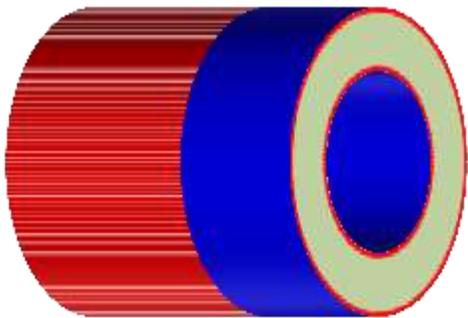
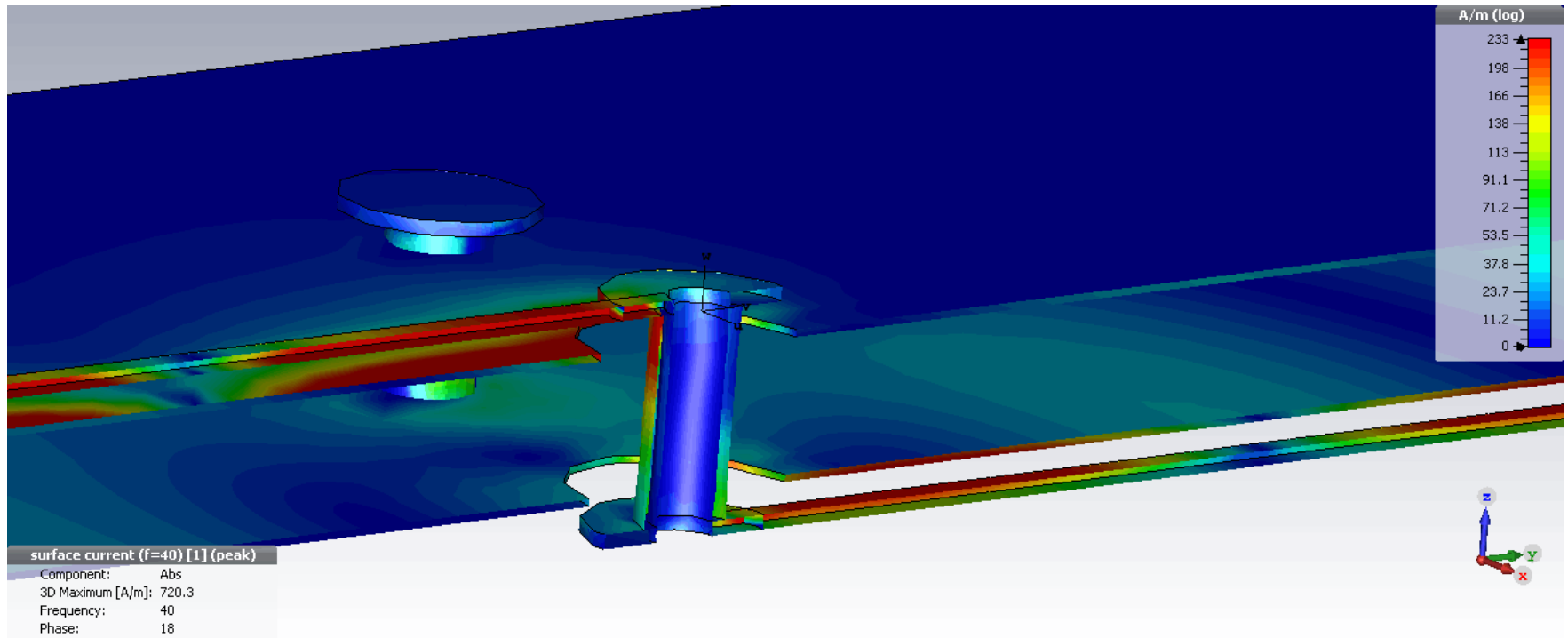


Differential pair with **via stitching**  
Return current path close



# AC Losses

## Current in a Via

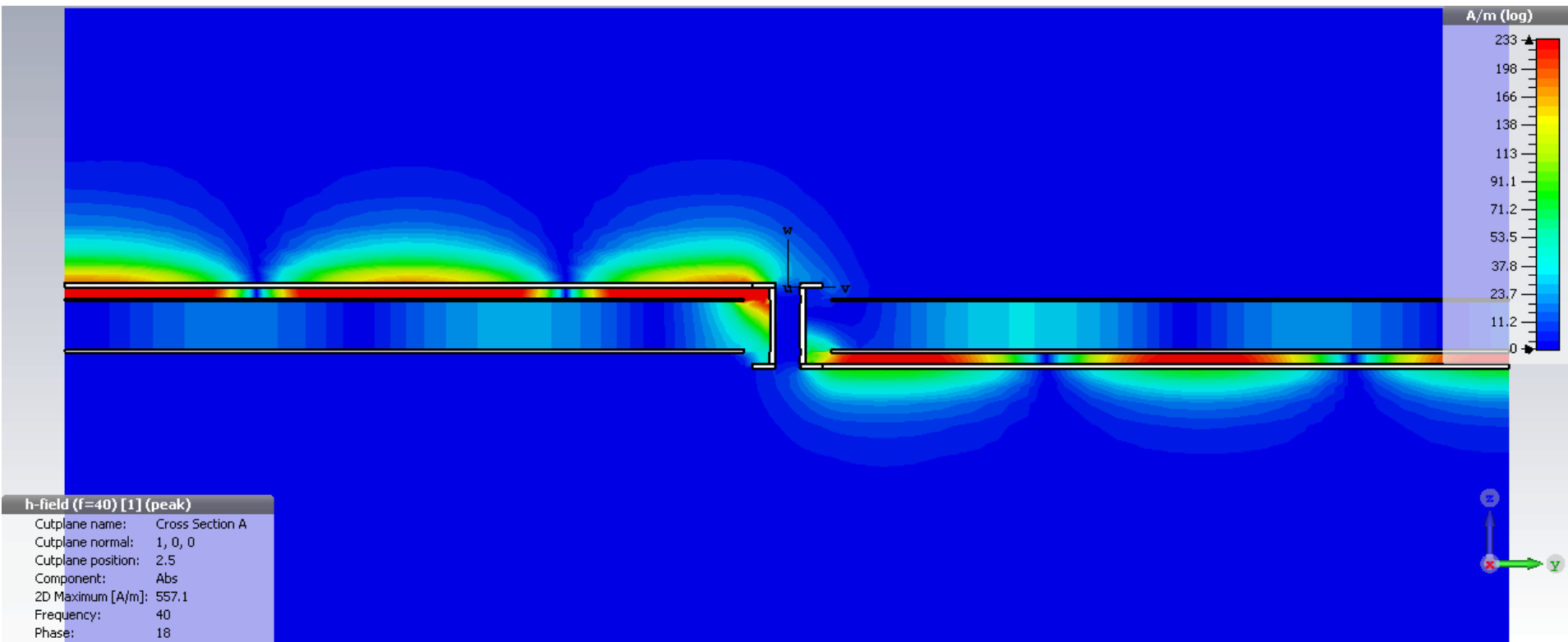


Drill size  
Current flows on the  
outside of the hole



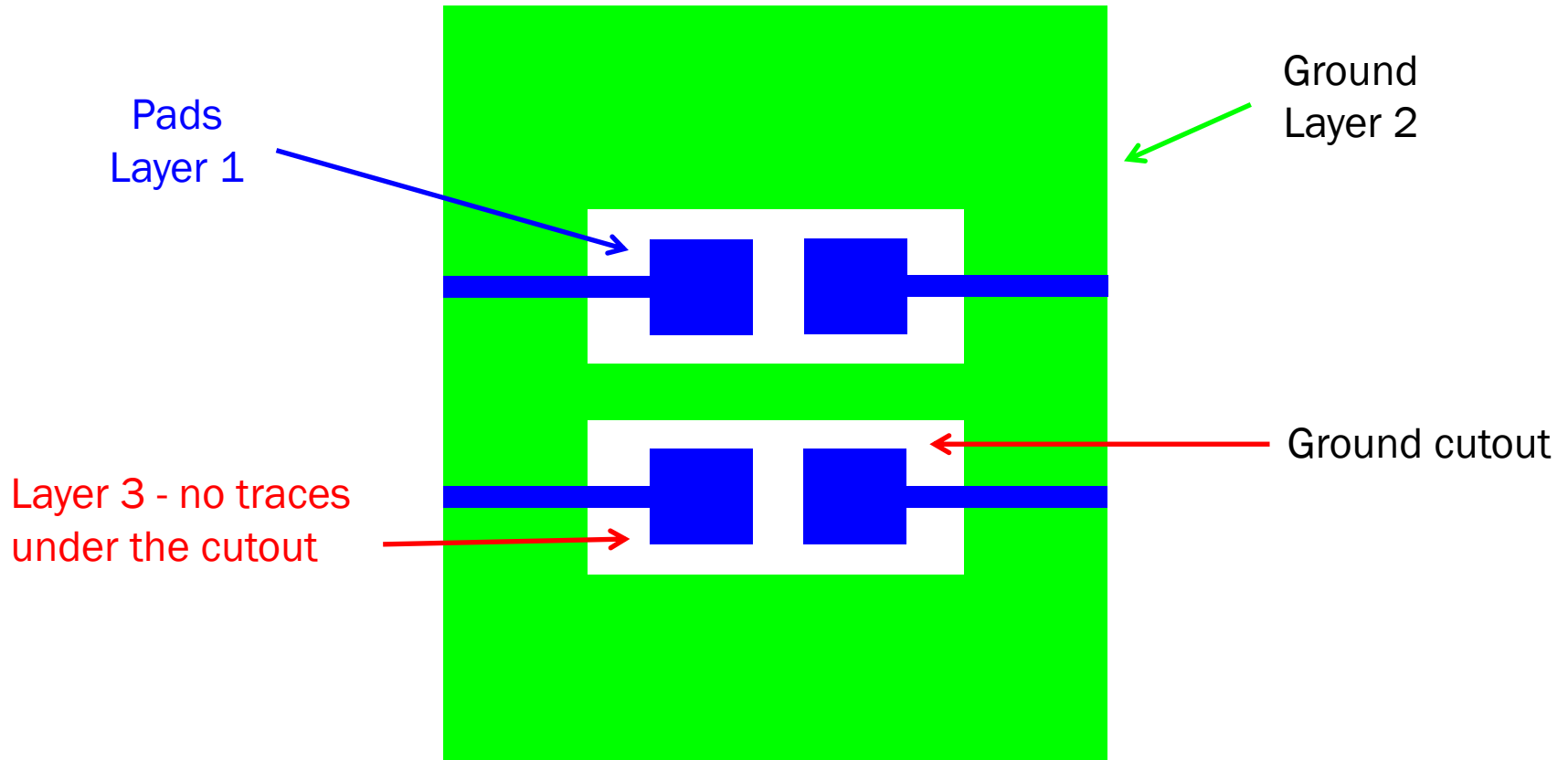
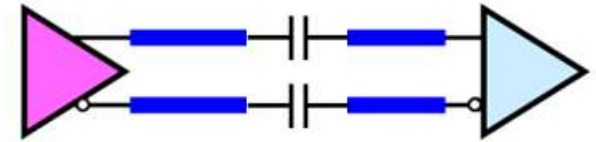
# AC Losses

## Current in a Via



# Differential Pair Capacitors

## Mounting Capacitance of Pads



Do not forget placement tolerance

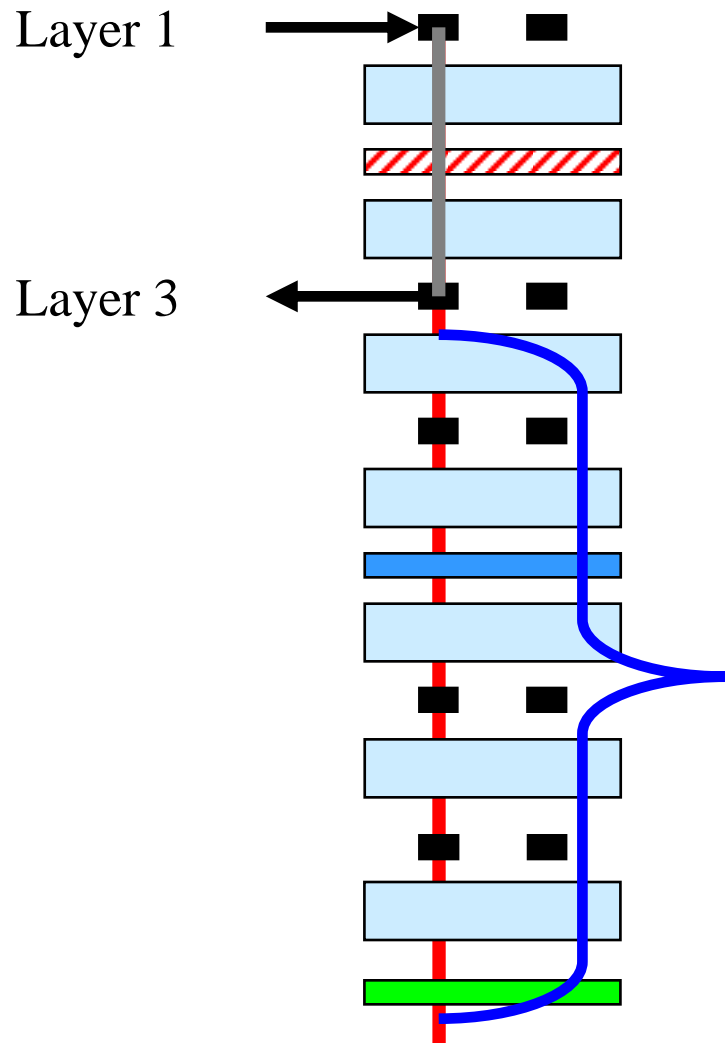
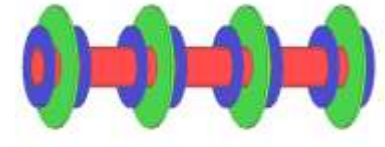


2 - 4mils / 50 - 100  $\mu\text{m}$



# Via Properties

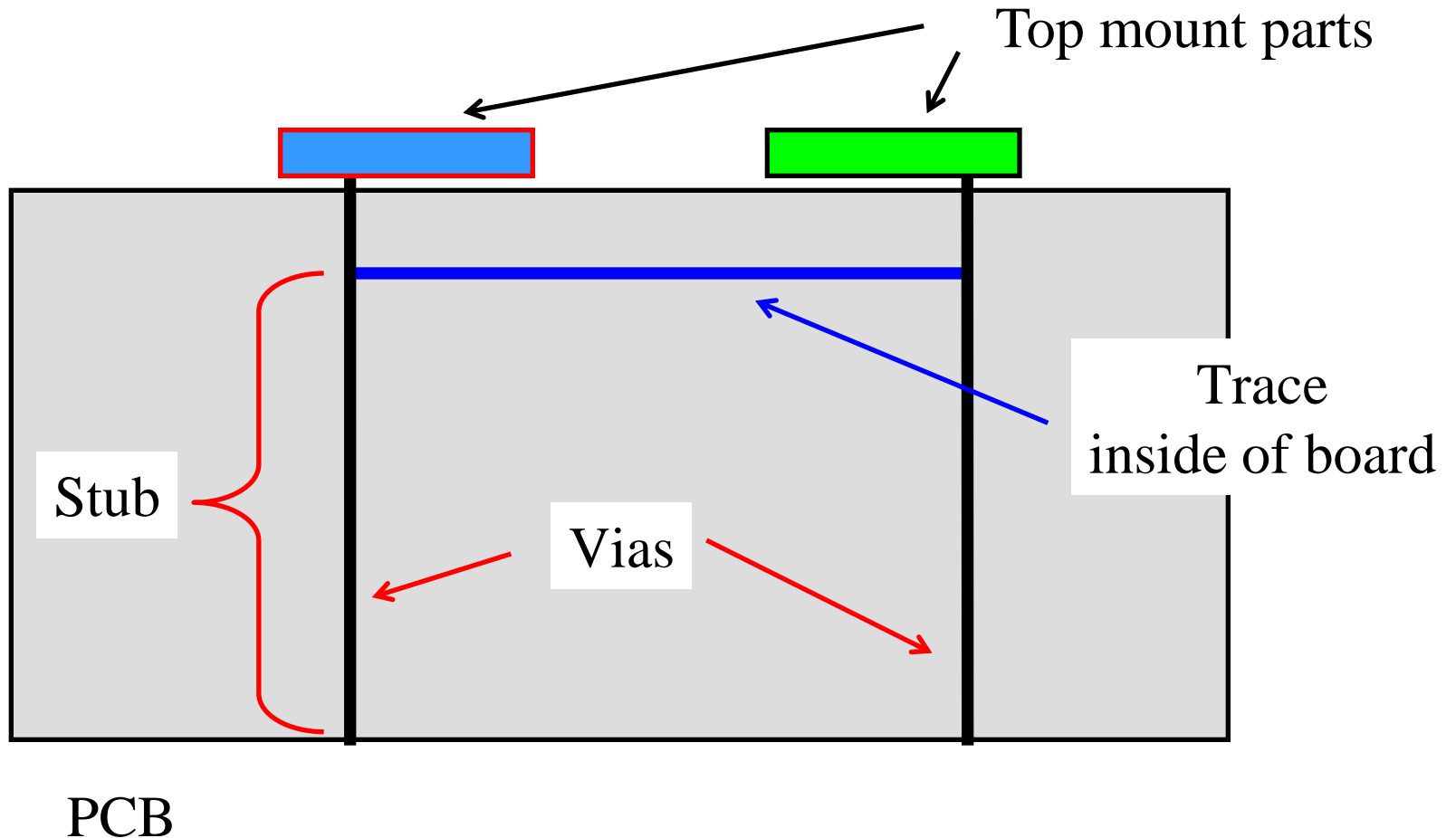
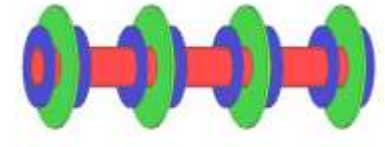
## Stub Length



When is this length  
important

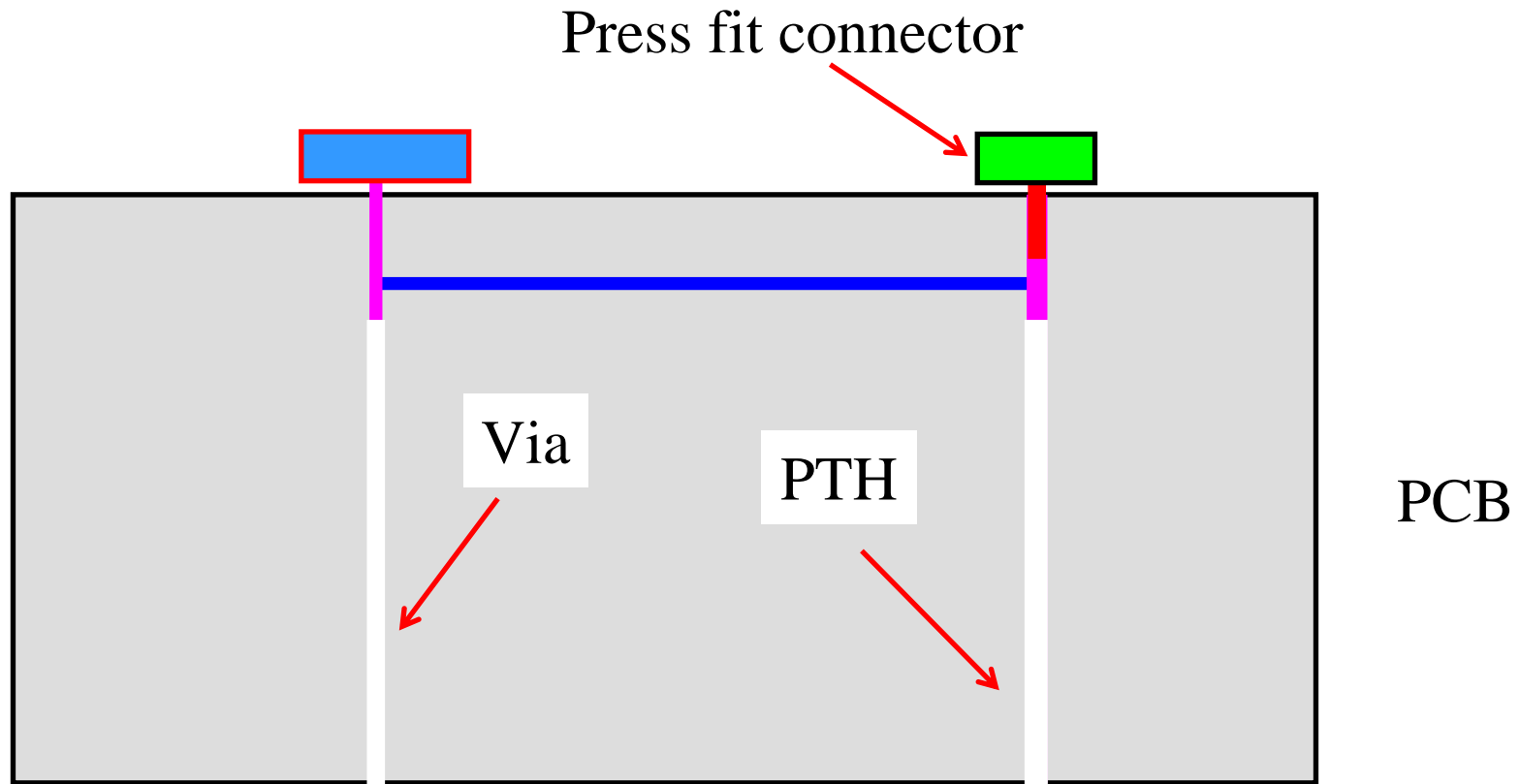


# Via Stubs Bad Routing



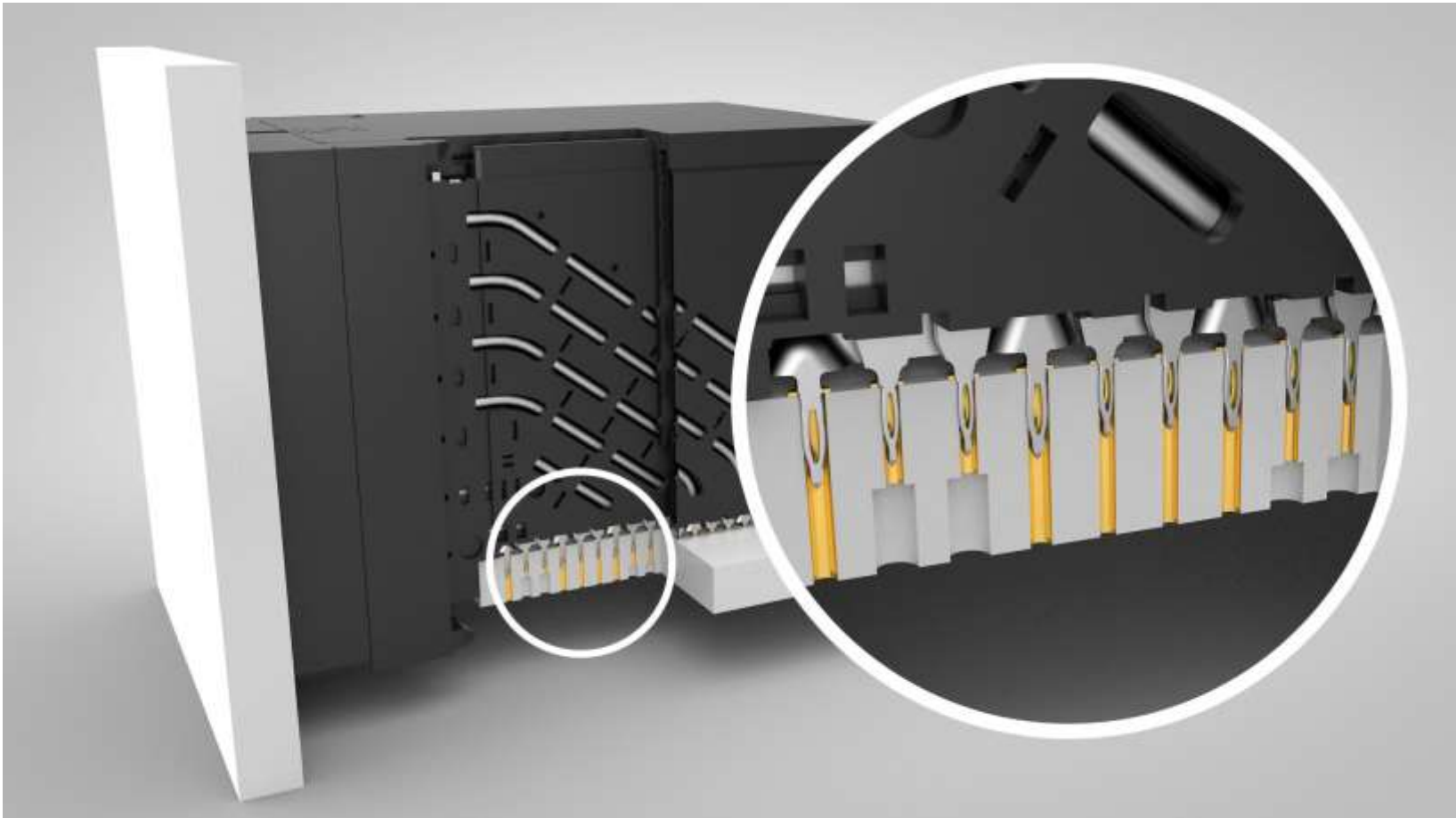
# Via & PTH (Plated Thru Hole) Stubs

## Backdrilling



# Via & PTH (Plated Thru Hole) Stubs

## Press Fit Connectors

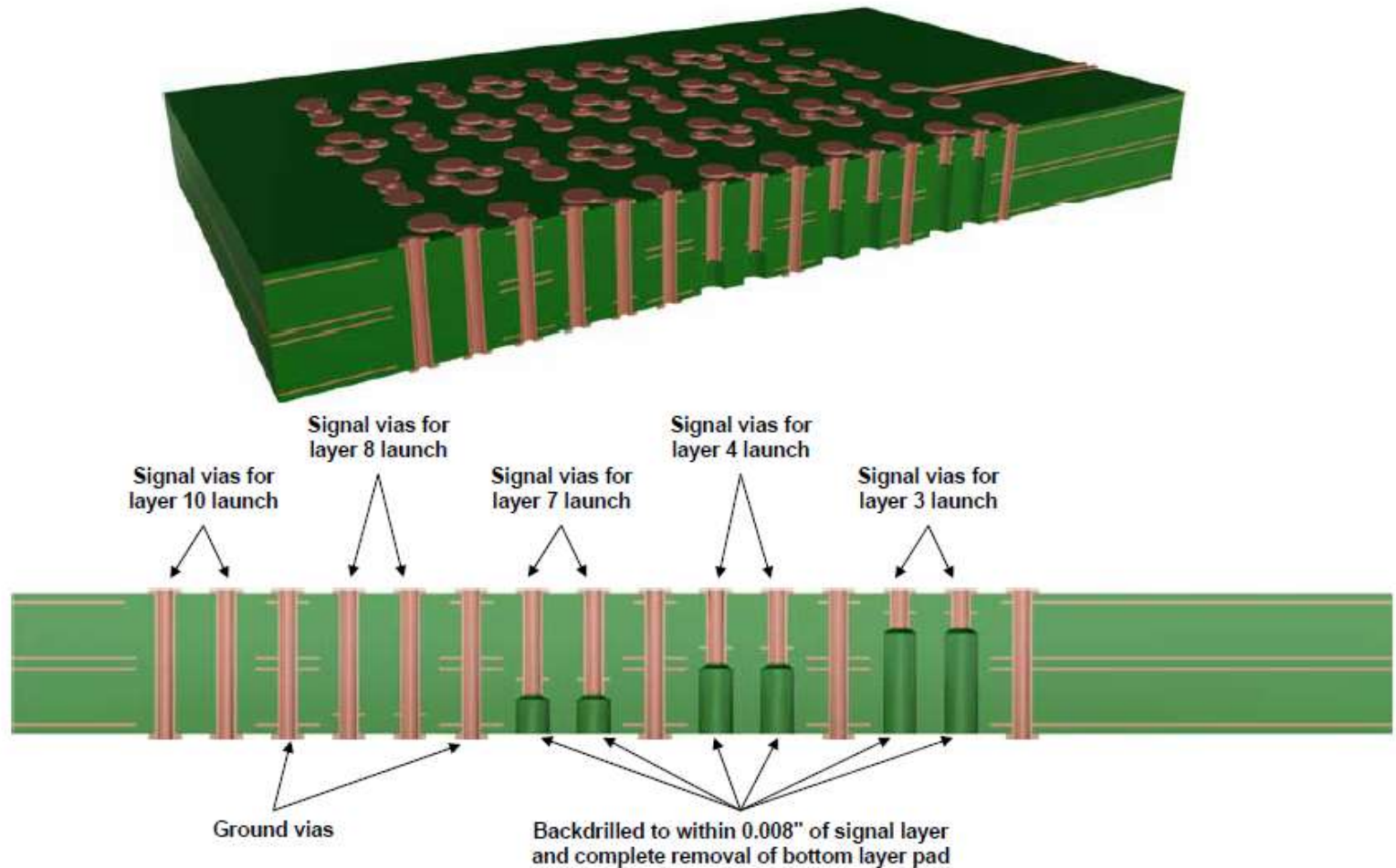


Samtec has many Press fit connectors



# Backdrilling Options

## Notice Layers 8 & 10



# PCB Performance

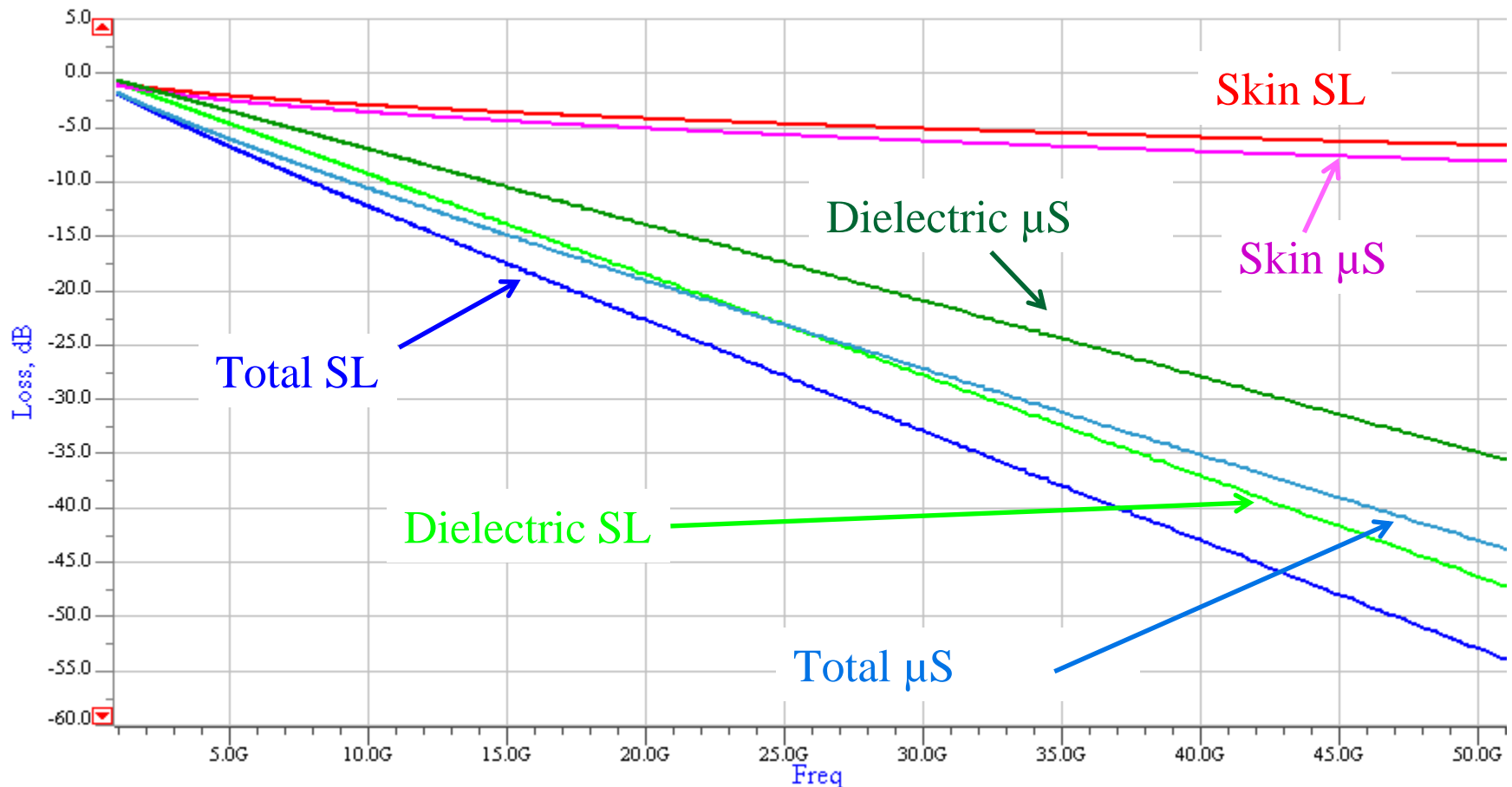
## Relative PCB Material Cost

Material Name	Cost-Index-36 layer line card	Cost-Index-22 layer backplane	Loss-Df- 10GHz	Skew Optimized
370-HR	1.00	1.00	0.02200	No
IS415	1.14	1.12	0.01200	No
FR408HR	1.65	1.62	0.00980	No
I-Speed	1.24	1.27	0.00700	No
Nelco-13 EP	2.37	2.30	0.00900	No
Megtron-4	1.63	1.69	0.00800	No
I-Speed IS	2.20	2.23	0.00550	Yes
Gigasync	2.86	2.90	0.00800	Yes
Nelco-13 EPSI	3.52	3.54	0.00800	No
I-Tera	2.82	2.82	0.00320	No
TerraGreen	3.03	3.02	0.00300	No
Megtron-6	3.32	3.51	0.00430	No
Tachyon/100G	4.09	4.39	0.00200	No



# AC Losses 10 in / 25 cm Trace

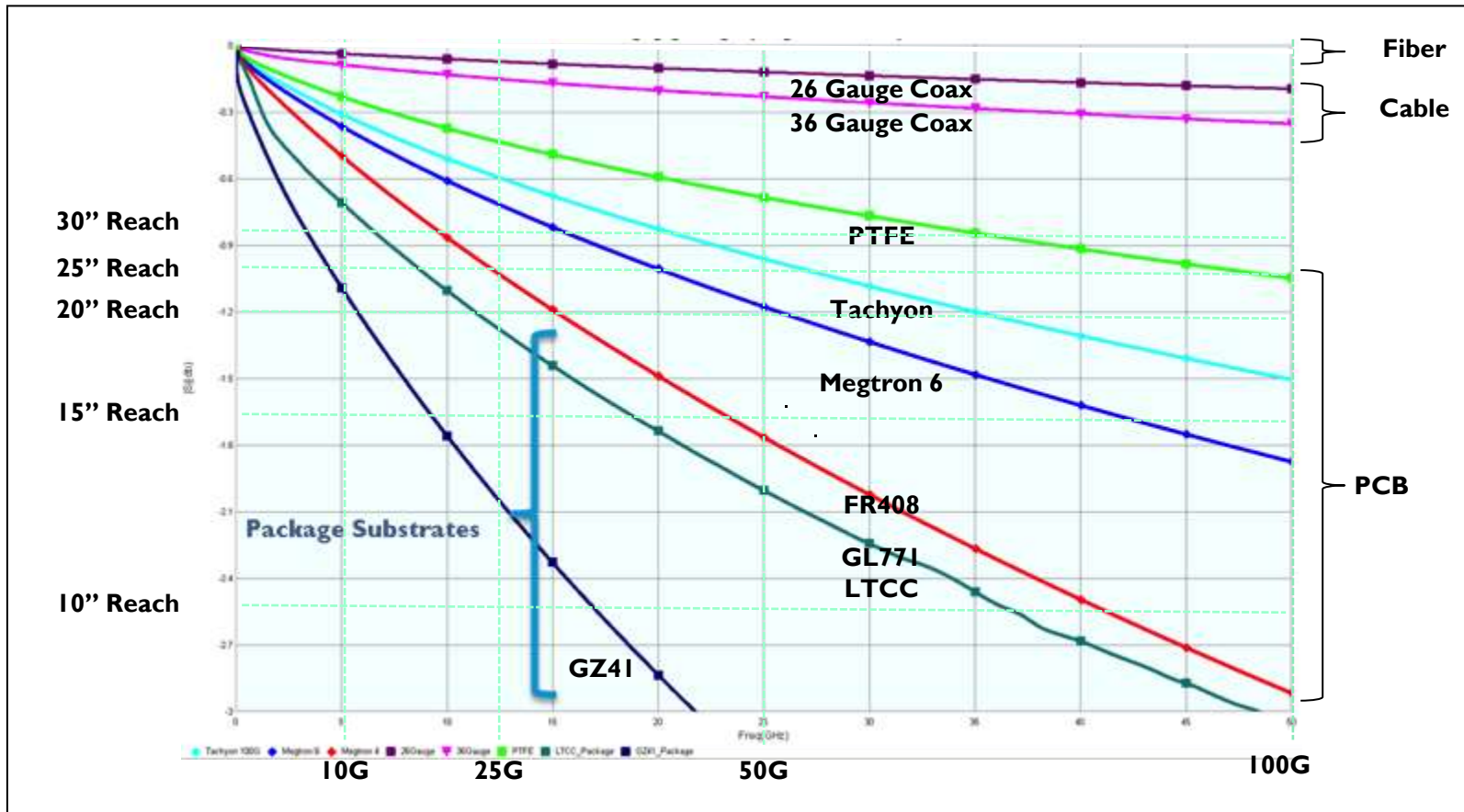
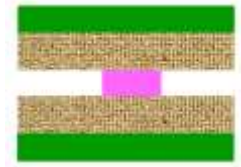
Loss vs Frequency: 1 GHz  $\rightarrow$  50 GHz



Microstrip (μS) vs Stripline (SL)



# AC Losses Stripline Trace Normalized to One Inch

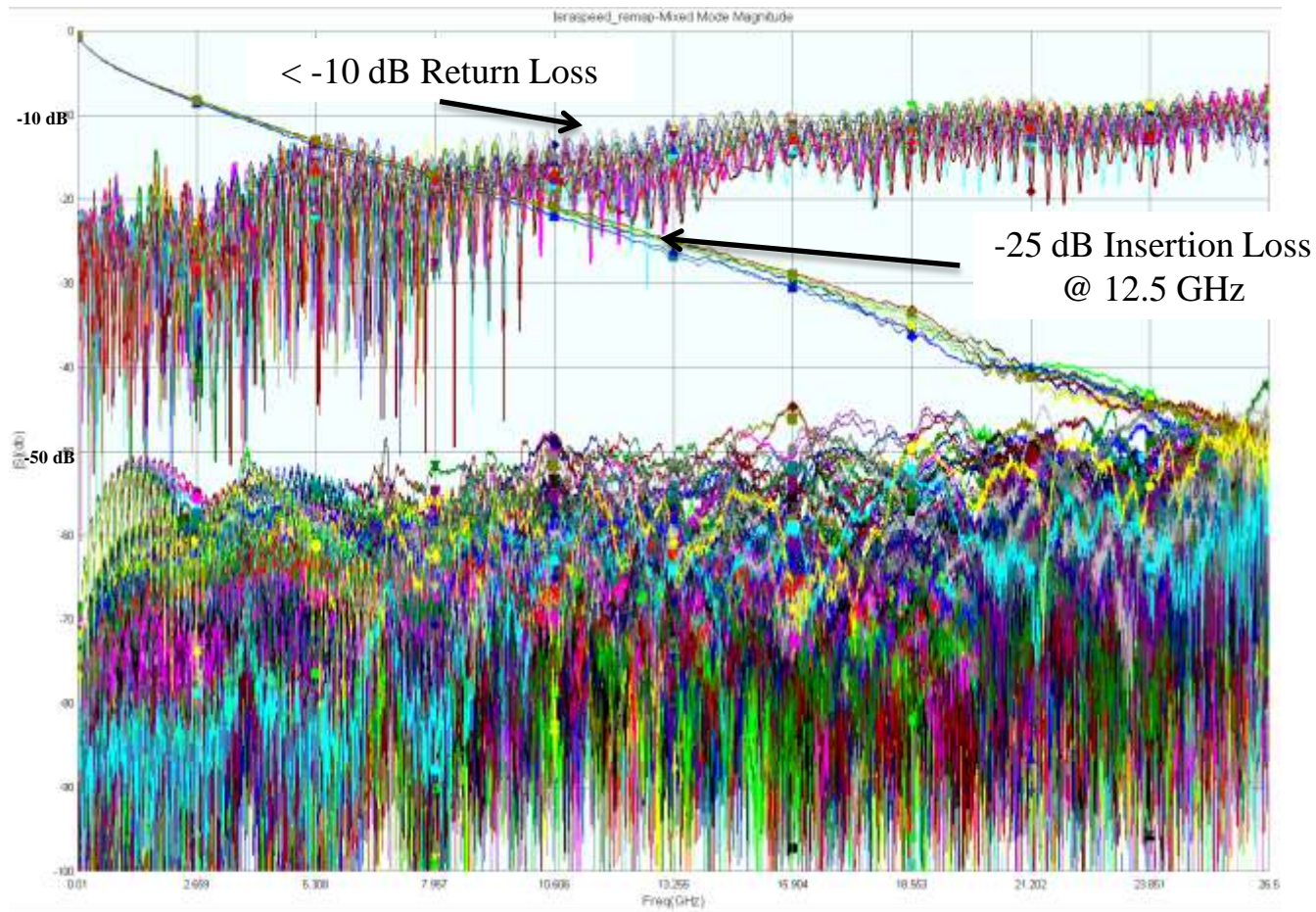


Normalized to 1 inch





# Teraspeed Examax 29 Inch Total Length Backplane Eight Adjacent Differential Pairs

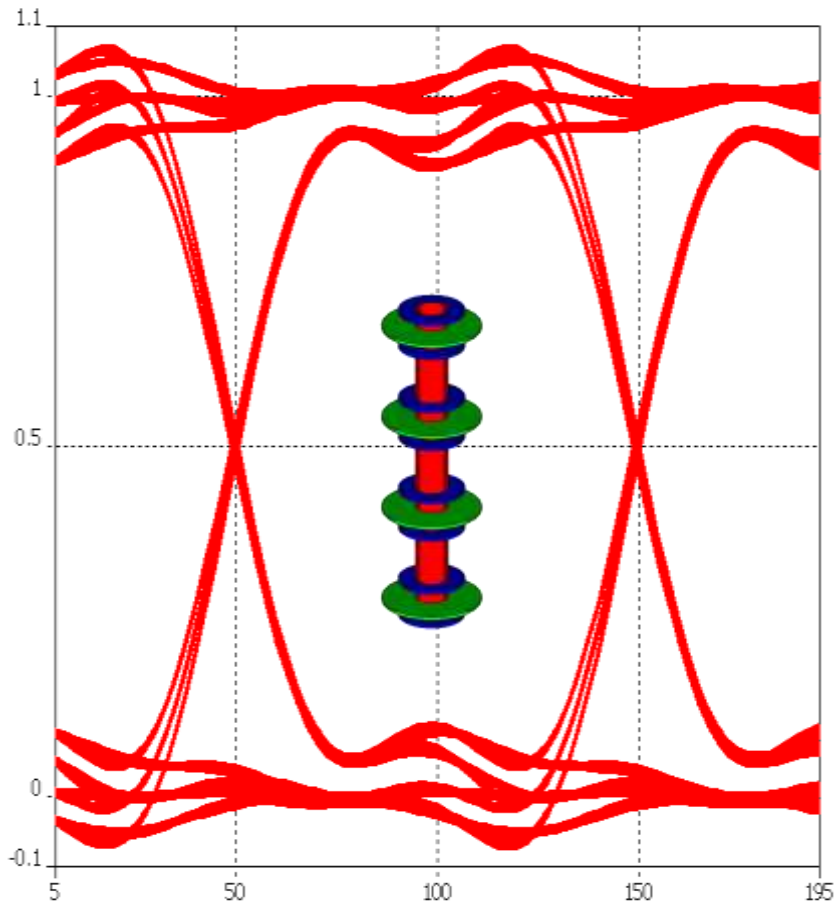


Low Crosstalk

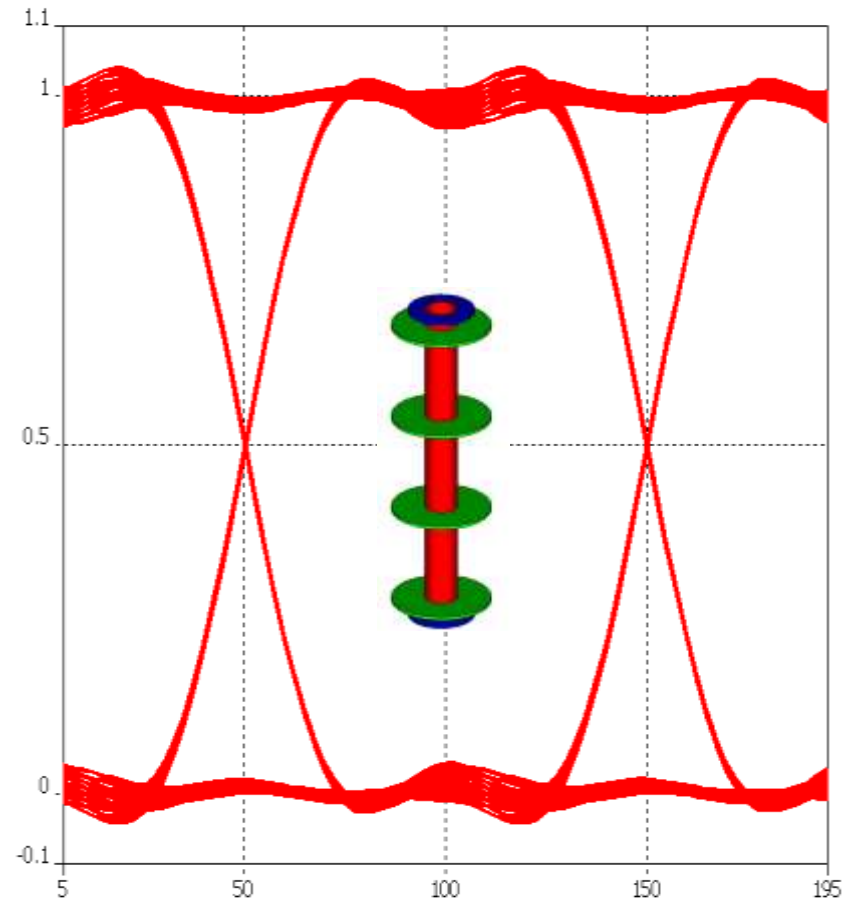


# Via Properties

## 12 Layer Better Pad Stack



Normal via

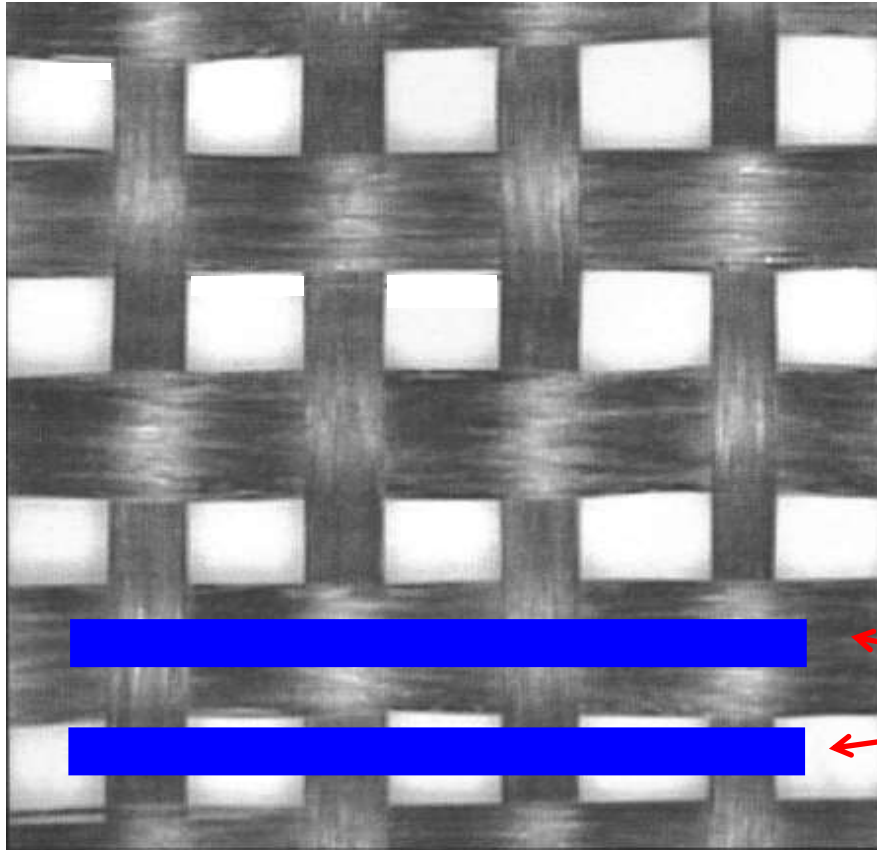


High speed via



# Fiber Weave Effect FR4 Material Top View

$$v = \frac{v_{\text{light}}}{\sqrt{\epsilon_r}}$$



Pitch is 16.7 mils

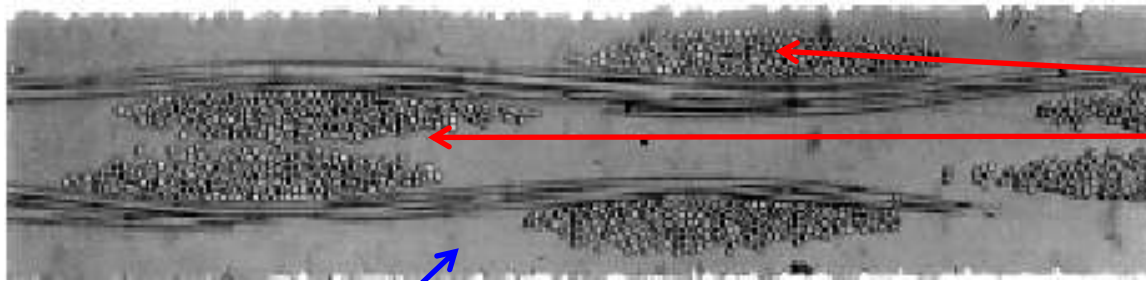
Different  $\epsilon_r$ 's  
then different  
trace velocity

1080



# Fiber Weave Effect FWE

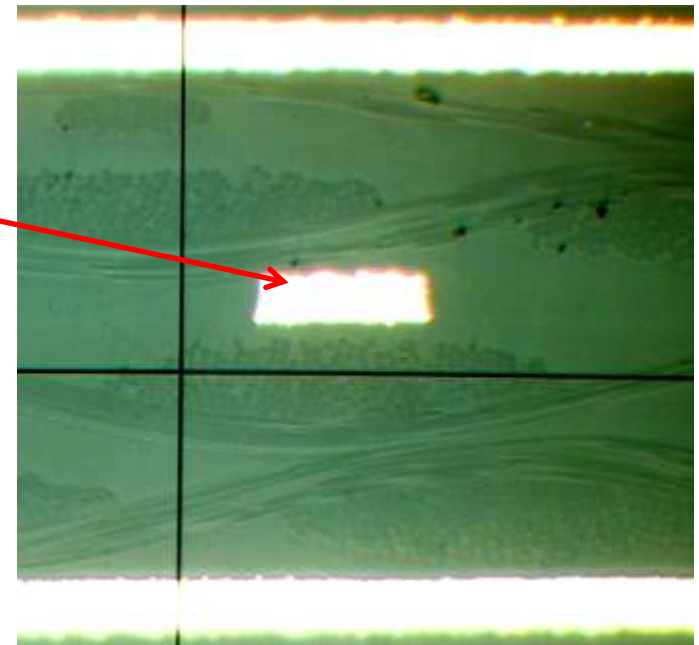
## FR4 Material Side View



Fiberglass  
Bundles  
 $\epsilon_r = 6.6$

Epoxy  
 $\epsilon_r = 3.6$

5mil / 125  $\mu\text{m}$  trace

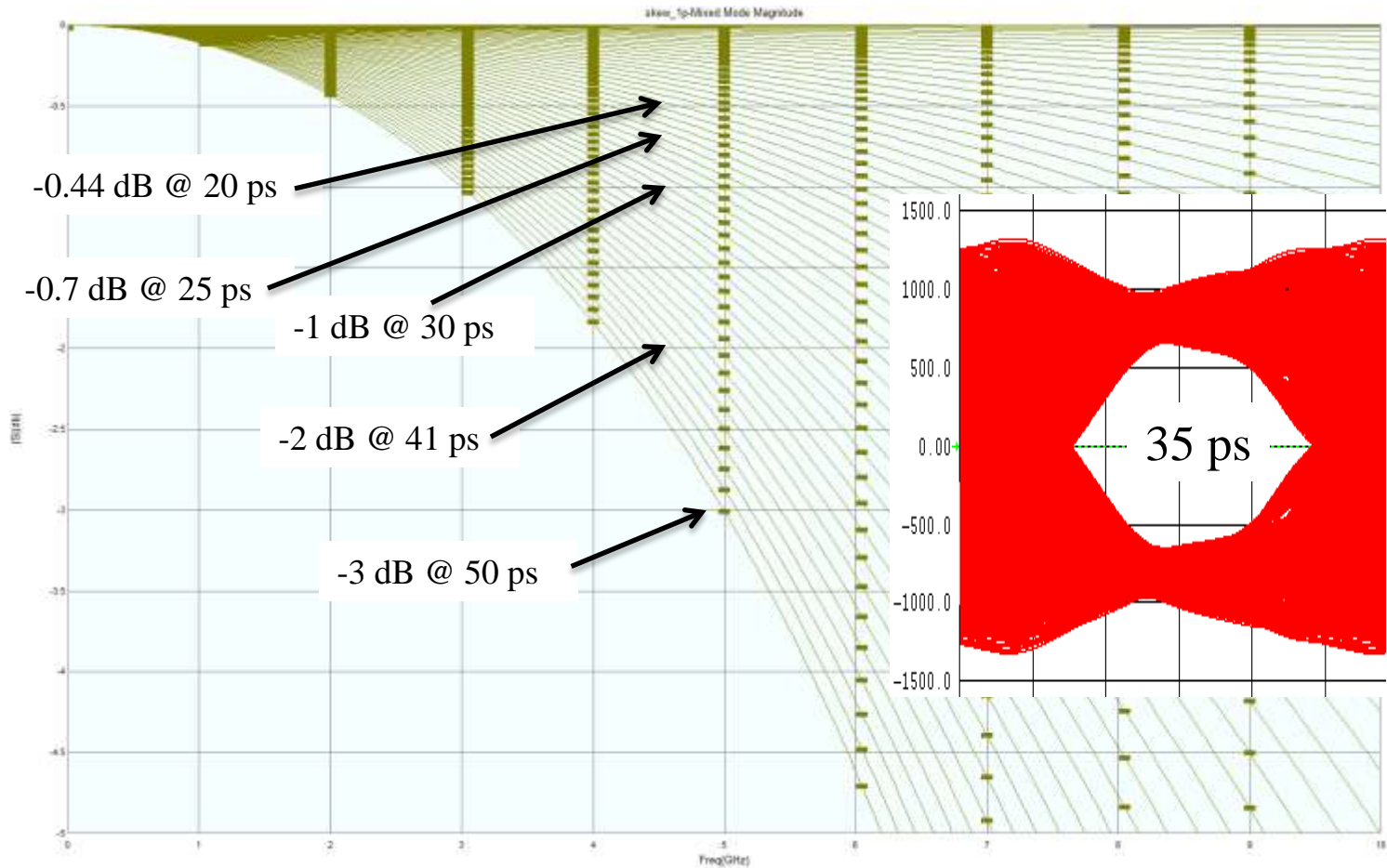


Non-homogeneous material has  
 $\epsilon_r$  variation due to glass/epoxy ratio



# Fiber Weave Effect Skew & Insertion Loss

## Ideal Insertion Loss Penalty vs. Skew (ps) for 10G



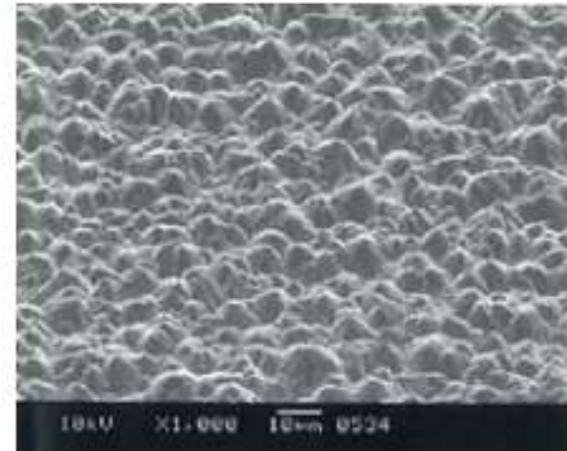
Skew loss becomes significant above 25 ps for 10 Gbps. These results can be scaled for different bit rates. For 6.25 Gbps -3 dB loss would occur at a skew of 80 ps, and -0.7 dB of loss at 40 ps of skew.





# PCB Problems

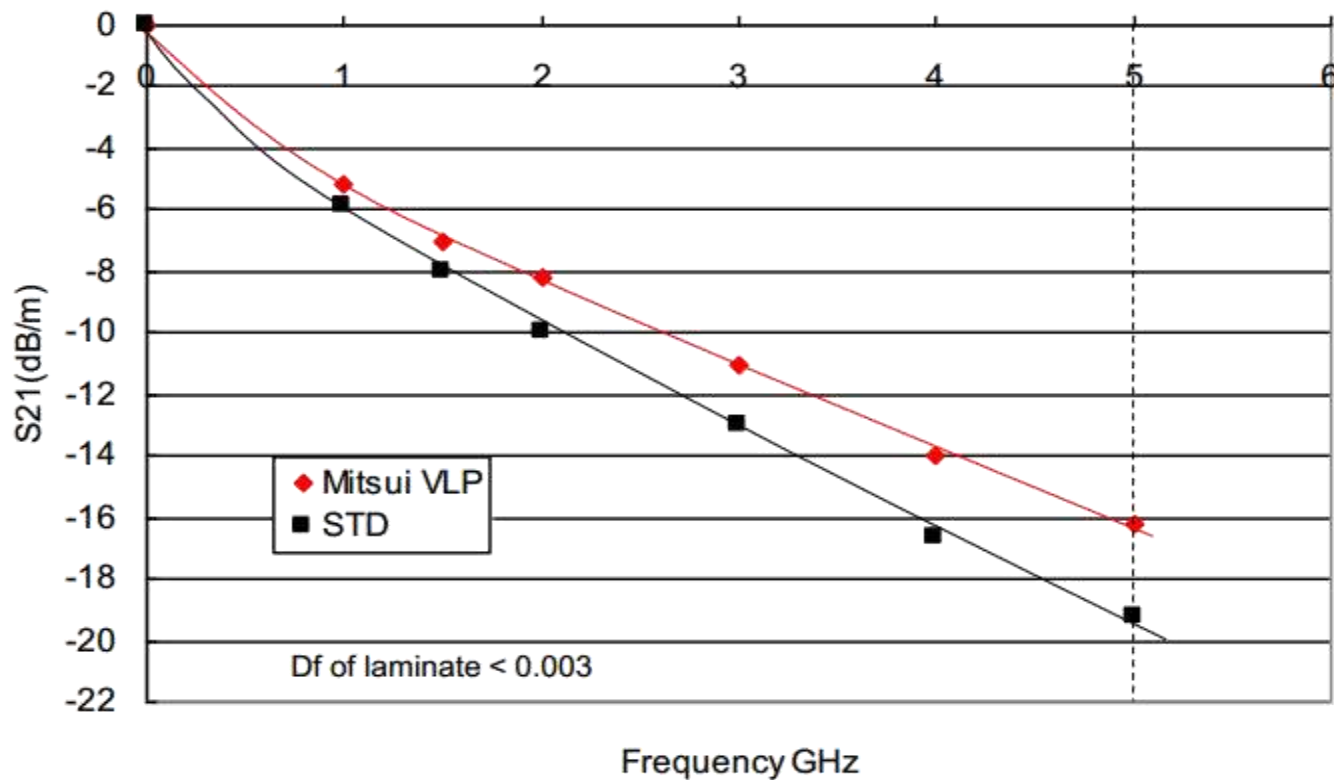
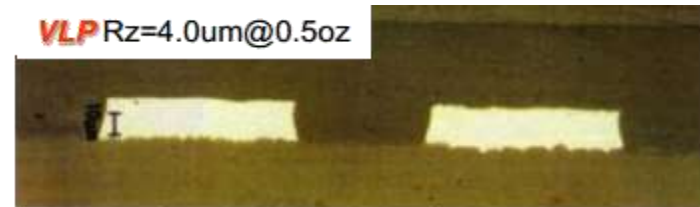
## Copper Roughness



How “lossy” is the trace

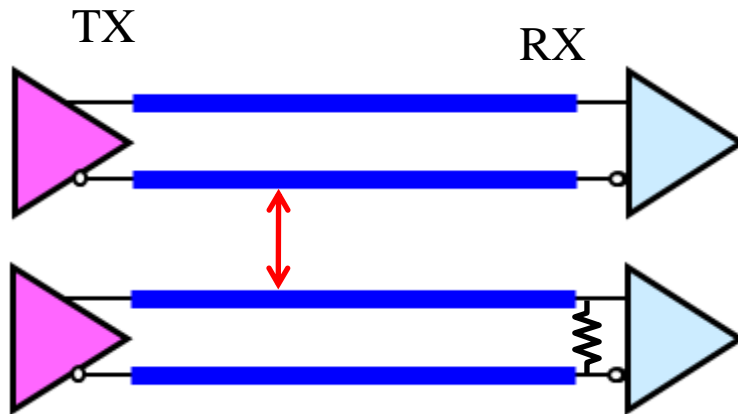
# PCB Problems

## Copper Roughness - Losses



# Differential Pair Rules

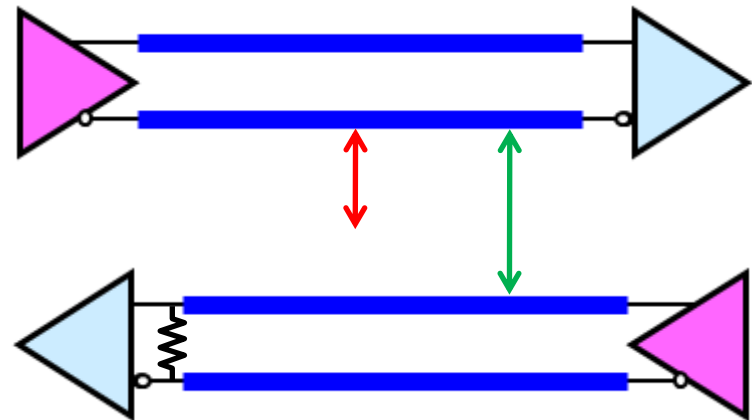
TX/TX, RX/RX or Larger Spacing



## Crosstalk

TX aggressor to TX victim

- Reverse crosstalk is reflected by  $R_s$  of driver then smaller or  $R_s = Z_{odd}$  then no reflections
- Forward and reflected reverse are smaller at the receiver by board loss  $D_F$



## Crosstalk

TX aggressor to RX victim

- Reverse crosstalk is terminated by  $Z_{Diff}$  so full voltage NEXT at RX





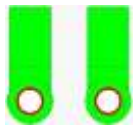
# Capacitor Mounting Inductance

## What Mounting Do You Use?

0402  
pH



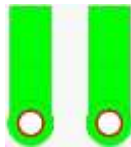
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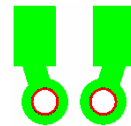
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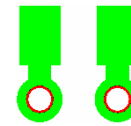
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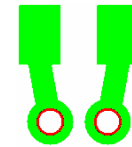
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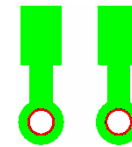
323



337



446



456



347



437



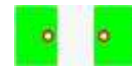
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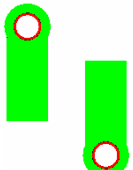
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171



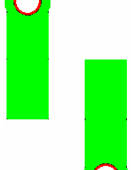
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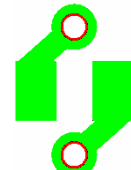
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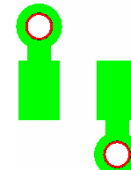
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380



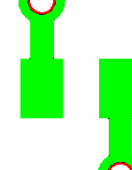
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356



502



476



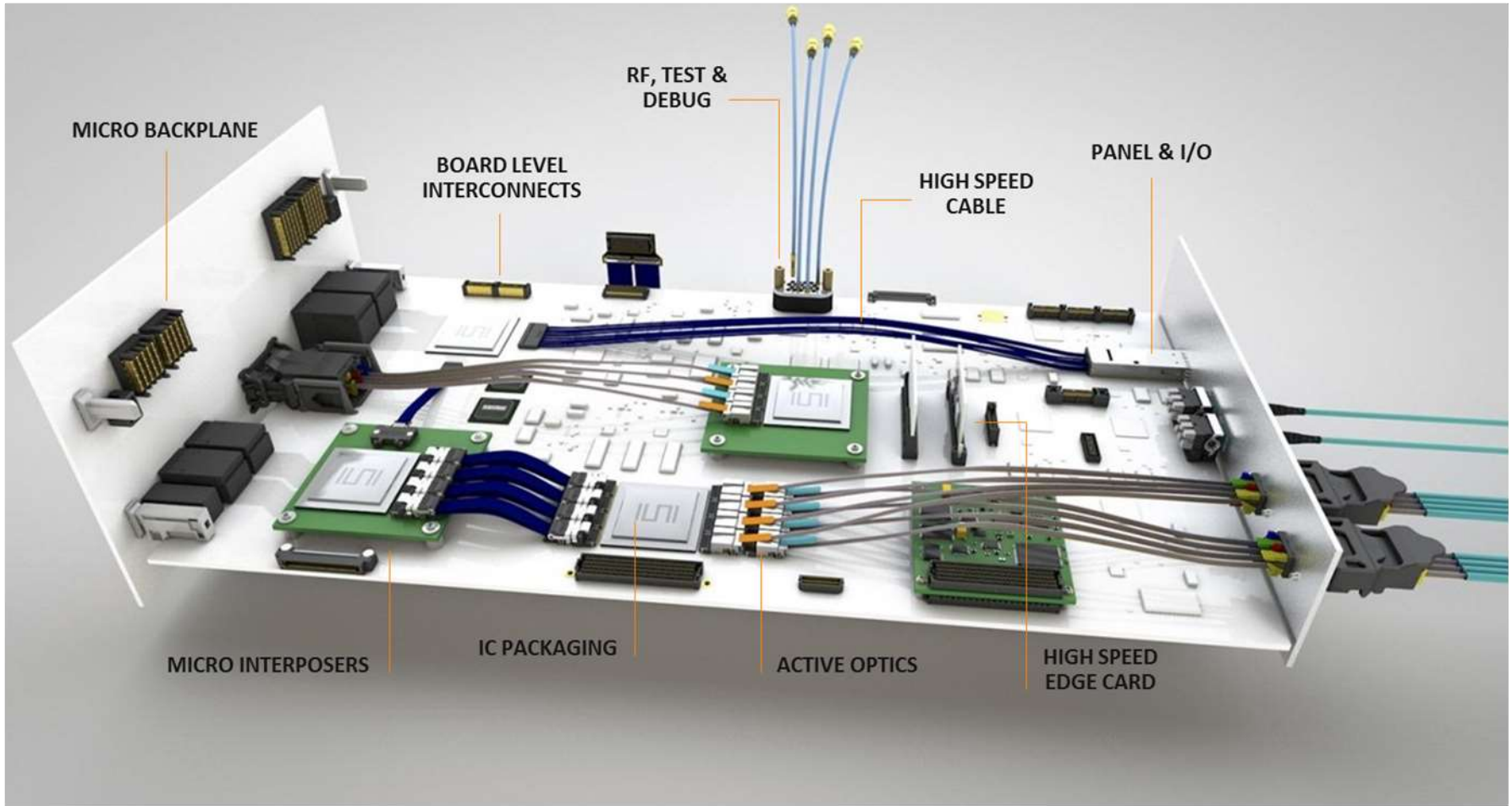
# Functional or NOT

## Simulate, Simulate and Simulate More

- How do you know if your design will work?
- Higher speeds means rules of thumb don't work
- Many PCB designers think that the rules that they used at 8 Gbp/s will work at 16, 20, 24, 28+
- Faster – need a **SI/PI engineer**
  - Part of the team
  - SI/PI consulting



# Full Signal Channel Solutions



Please visit [www.samtec.com](http://www.samtec.com) for more information





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